

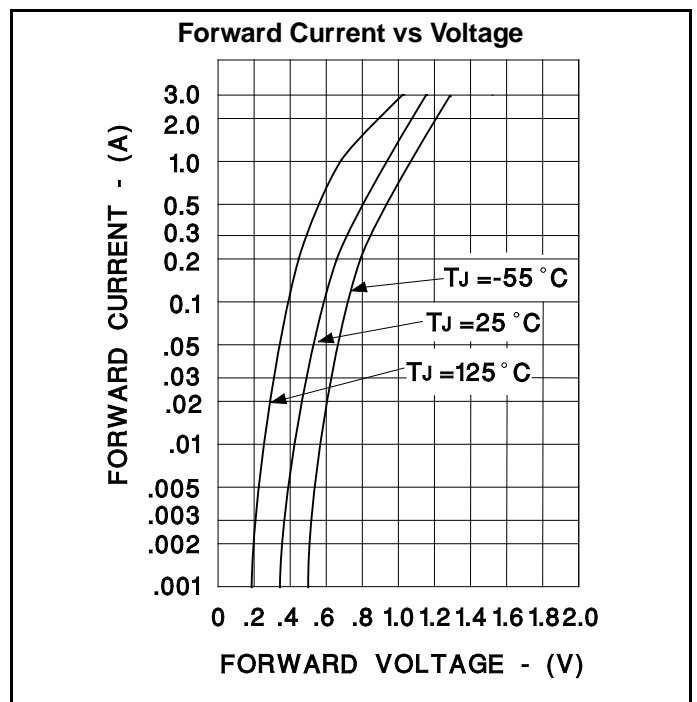
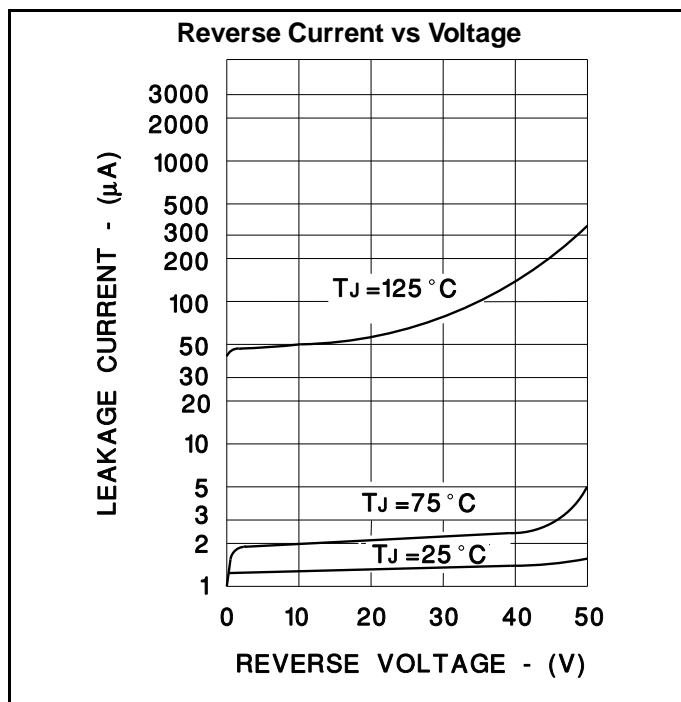
ABSOLUTE MAXIMUM RATINGS

Peak Inverse Voltage (per Diode)..... 50V
 Diode-to-Diode Voltage..... 80V
 Peak Forward Current
 UC1611..... 1A
 UC3611..... 3A
 Power Dissipation at TA = +70°C..... 1W
 Storage Temperature Range..... -65°C to +150°C
 Lead Temperature (Soldering, 10 Seconds)..... +300°C
 Note: Please consult Packaging Section of Databook for thermal limitations and considerations of package.

ELECTRICAL CHARACTERISTICS: All specifications apply to each individual diode. TJ = +25°C except as noted.
 TA = TJ.

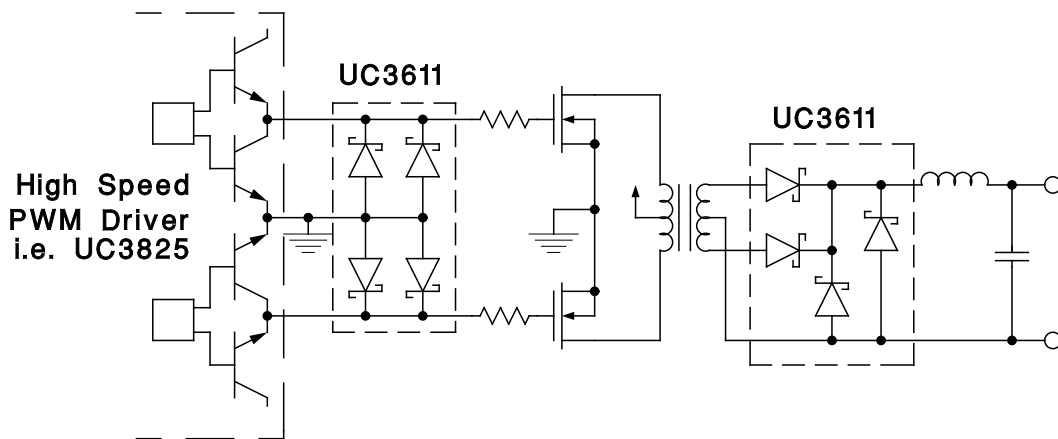
PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Forward Voltage Drop	IF = 100mA	0.3	0.4	0.7	V
	IF = 1A		0.9	1.2	V
Leakage Current	VR = 40V		0.01	0.1	mA
	VR = 40V, TJ = +100°C		0.1	1.0	mA
Reverse Recovery	0.5A Forward to 0.5A Reverse		20		ns
Forward Recovery	1A Forward to 1.1V Recovery		40		ns
Junction Capacitance	VR = 5V		100		pF

Note: At Forward currents of greater than 1.0A, a parasitic current of approximately 10mA may be collected by adjacent diodes.

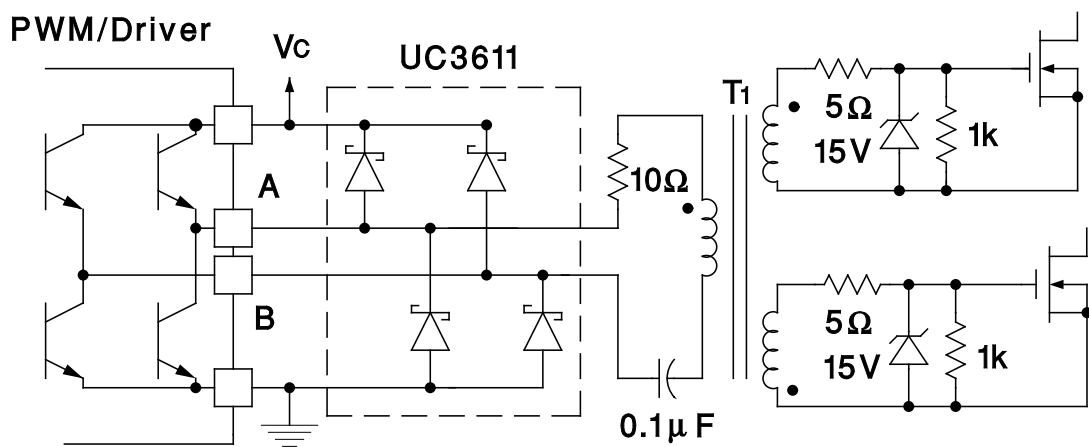


TYPICAL APPLICATIONS

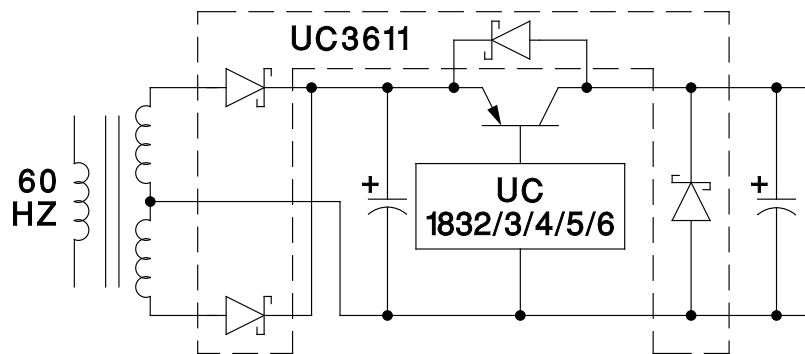
A. Clamp Diodes - PWMS and Drivers



B. Transformer Coupled Drive Circuits



C. Linear Regulations



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